

intel® Technical Advisory

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STL2 Server Board difficult installation of 1GHz heat sink clip on secondary CPU socket

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Products Affected

STL2, BTLBB

Description

It is difficult to install the heat sink clip included with 1GHz boxed Intel® Pentium® III processors for the PGA370 socket on STL2 server boards built with a secondary CPU socket from the manufacturer Molex, due to the very close proximity of the capacitor at location 9D8.

This issue is not present on STL2 server boards built with a secondary CPU socket from the manufacturers AMP or Foxconn, because the tab to which the heat sink clip attaches is slightly smaller than the tab on the Molex connectors.

Root Cause

This issue was caused by a design oversight.

Corrective Action / Resolution

This issue will be fixed in a future FAB spin of the STL2 server board. The capacitors near the secondary CPU socket are being moved slightly to allow for easier heat sink clip installation.

Workarounds

It is possible to install the heat sink clip included with 1GHz boxed Intel® Pentium® III processors for the PGA370 socket on STL2 server boards built with a secondary CPU socket from the manufacturer Molex.

To make the installation as easy as possible, it is recommended that the processors and heat sinks be installed before the STL2 server board is installed into the chassis. When installing the processors and heat sinks, the STL2 server board should be placed on a flat, firm, ESD protected surface. Follow the installation procedures included with the 1GHz boxed Intel® Pentium® III processors for the PGA370 socket when installing the heat sink clip. It is necessary to apply force to the heat sink clip tab until the clip is latched into place.

Please contact your Intel Sales Representative if you require more specific information about this issue.

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